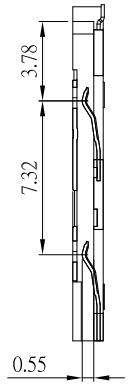
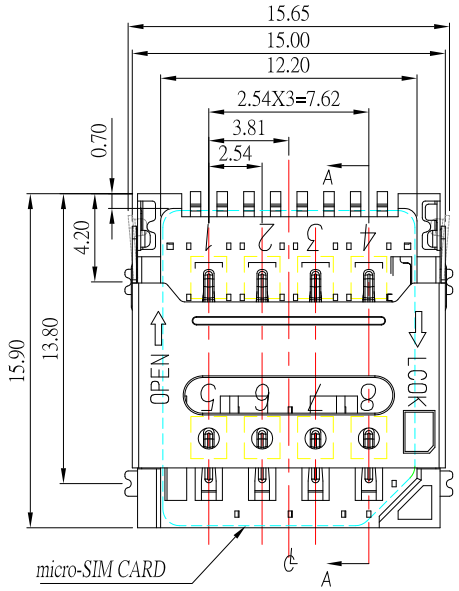
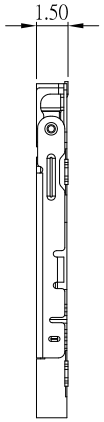
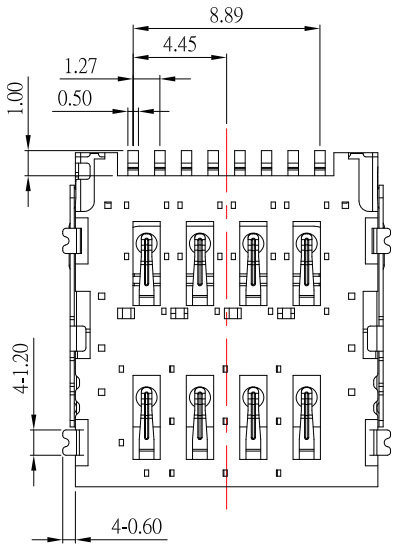
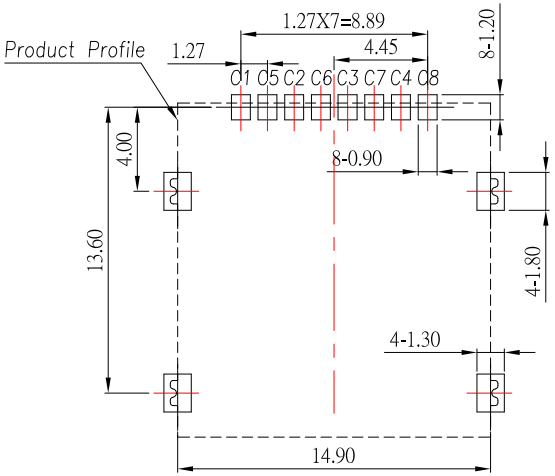


SECTION: A–A

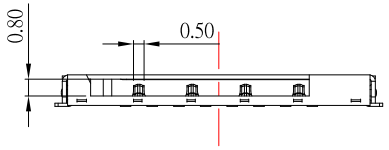


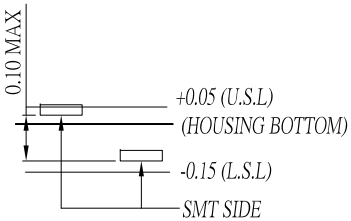




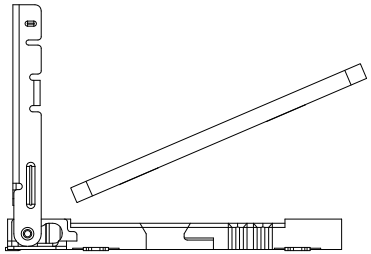


PCB LAYOYT

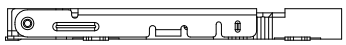




COPLANARITY



STEP 1 INSERT Micro–SIM CARD



STEP 2 PUSH THE SHELL

STEP 3 FINISH

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED

SPECIFICATION

Electrical :

1.Contact Resistance: 60 mΩ Max.

2.Insulation Resistance: 1,000 MΩ Min.

3.Dielectrec Withstanding Voltage: 500 V AC

Material:

1.Housing: Thermoplastic

2.Contact: Phosphor Bronze

3.Shell: SUS

Finish:

1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall

2.Shell: Nickel under Plated surface laye

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新尺寸及更新爲A0版	Jack	032218

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY: Jack Lu	DATE 03/22/18	MAT'L	
CHECKED BY: Jacky Chen	DATE 03/22/18	FINISH	
APPROVED BY: Tony Kao	DATE 03/22/18	SCALE 1 : 1	SHEET NO. 1 of 1

TITLE	CONNECTOR
MODLE	MICRO SIM 8PIN H1.5 掀蓋
DWG NO.	MSIM-08H150-S267
PART NO.	MSIM-08H150-S267
SIZE	A4
VER	A0